

15. The flip chip interconnection structure of claim 10 wherein the second member comprises a via opening.

16. The flip chip interconnection structure of claim 10 wherein the second member has a plated finish.

17. The flip chip interconnection structure of claim 10, said bump comprising one of a set of such bumps.

RESPONSE TO RESTRICTION REQUIREMENT

Responsive to the Office Action mailed May 31, 2002 (Restriction Only), Applicants elect Group I, claims 1-9 for prosecution in this application.

REMARKS

Preliminary Amendment

In the May 31, 2002 Office Action the Examiner noted, correctly, that "[a]lthough claims 12-17 are referred as method claims, it appears to be directed to device." The Preliminary Amendment herein replaces "method" with -- flip chip interconnection structure -- in each of these claims. No new matter is introduced by any of these amendments, and entry thereof is respectfully requested.

This Preliminary Amendment is accompanied by a Supplemental Information Disclosure Statement. This Supplemental IDS is being filed under 37 CFR 1.97(b) before a first Office Action on the merits and, accordingly it is believed that it qualifies under 37 CFR 1.97.

Restriction Requirement

The Examiner required restriction to one of:

Group I, Claims 1-9, said to be drawn to a "method of manufacturing a semiconductor device";


Group II, Claims 15-19, said to be drawn to a "semiconductor device".

Applicants elect Group I, claims 1-9, for prosecution in this application. Applicants note that these claims are drawn to a method for forming a "flip chip interconnection structure" and to a flip chip interconnection structure made by the method.

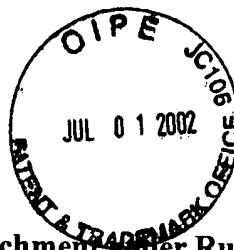
It is believed that no extension of time or fee therefor is required in connection with the filing of this paper. If the Examiner determines that an extension of time is required in connection with the filing of this paper, petition is hereby made therefor, and the Commissioner is authorized to charge the fee to Deposit Account 50-0869 (Order No. CPAC 1003-1).

If the Examiner determines that a conference would facilitate prosecution of this application, the Examiner is invited to telephone Applicants' representative, undersigned, at the telephone number set out below.

Respectfully submitted,

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Attachment under Rule 1.121
(Claims)

Claims 12 - 17 are amended as follows:

12. (Amended) The [method] flip chip interconnection structure of claim 10 wherein the deformable material of the first member comprises gold.

13. (Amended) The [method] flip chip interconnection structure of claim 10 wherein the second member comprises a surface pad.

14. (Amended) The [method] flip chip interconnection structure of claim 10 wherein the second member comprises a lead.

15. (Amended) The [method] flip chip interconnection structure of claim 10 wherein the second member comprises a via opening.

16. (Amended) The [method] flip chip interconnection structure of claim 10 wherein the second member has a plated finish.

17. (Amended) The [method] flip chip interconnection structure of claim 10, said bump comprising one of a set of such bumps.

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